



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IR3888BMTRPBF	<b>Issued</b>	08. April 2022
<b>MA#</b>	MA005584297		
<b>Package</b>	PG-IQFN-22-2	<b>Weight*</b>	85.38 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.210	0.25	0.25	2465	2465
chip_2	inorganic material	silicon	7440-21-3	0.393	0.46	0.46	4598	4598
chip_3	inorganic material	silicon	7440-21-3	1.552	1.82	1.82	18176	18176
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		115	
	non noble metal	zinc	7440-66-6	0.039	0.05		462	
	non noble metal	iron	7439-89-6	0.788	0.92		9230	
	non noble metal	copper	7440-50-8	31.997	37.48	38.46	374776	384583
wire	noble metal	gold	7440-57-5	0.356	0.42		4169	
	non noble metal	copper	7440-50-8	0.929	1.09	1.51	10878	15047
encapsulation	organic material	carbon black	1333-86-4	0.091	0.11		1061	
	plastics	epoxy resin	-	4.666	5.47		54655	
	inorganic material	silicondioxide	60676-86-0	40.546	47.48	53.06	474912	530628
leadfinish	noble metal	palladium	7440-05-3	0.003			31	
	noble metal	gold	7440-57-5	0.004			50	
	non noble metal	nickel	7440-02-0	0.077	0.09	0.09	905	986
plating	noble metal	silver	7440-22-4	0.588	0.69	0.69	6893	6893
solder	noble metal	silver	7440-22-4	0.078	0.09		916	
	non noble metal	tin	7440-31-5	0.156	0.18		1831	
	non noble metal	lead	7439-92-1	2.892	3.39	3.66	33877	36624
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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